

Title (en)

Composition, use thereof and method for electrodepositing gold containing layers

Title (de)

Zusammensetzung, ihre Verwendung und Verfahren zur galvanischen Abscheidung von Gold enthaltenden Schichten

Title (fr)

Composition, utilisation de la composition et procédé pour le dépôt galvanique de couches contenant de l'or

Publication

EP 2990507 A1 20160302 (EN)

Application

EP 14182083 A 20140825

Priority

EP 14182083 A 20140825

Abstract (en)

The present invention relates to a composition and method for electrodepositing gold containing layers using the composition and the use of mercapto triazole as additive. The composition contains a mercapto-triazole compound which acts as an anti-immersion additive. The composition and method are suited for depositing functional or hard gold or gold alloys that can be applied in the industry as contact material of electrical connectors for high reliability applications.

IPC 8 full level

C25D 3/48 (2006.01); **C25D 3/62** (2006.01); **C25D 21/18** (2006.01)

CPC (source: CN EP KR US)

C25D 3/48 (2013.01 - CN EP KR US); **C25D 3/62** (2013.01 - CN EP KR US); **C25D 21/18** (2013.01 - CN EP KR US)

Citation (applicant)

EP 2309036 B1 20130828 - ROHM & HAAS ELECT MAT [US]

Citation (search report)

- [XI] US 2004069641 A1 20040415 - ABE MIWA [JP], et al
- [XI] EP 2669407 A1 20131204 - BLUCLAD S R L [IT]
- [AD] EP 2309036 B1 20130828 - ROHM & HAAS ELECT MAT [US]
- [A] CN 102105623 A 20110622 - JAPAN PURE CHEMICAL CO LTD
- [A] EP 1728898 A2 20061206 - ROHM & HAAS ELECT MAT [US]

Cited by

US10577704B2; WO2016208340A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2990507 A1 20160302; CN 106661751 A 20170510; CN 106661751 B 20191112; EP 3186413 A1 20170705; EP 3186413 B1 20190206; JP 2017527700 A 20170921; JP 6726173 B2 20200722; KR 102315943 B1 20211021; KR 20170046651 A 20170502; SG 11201700461V A 20170330; TW 201615628 A 20160501; TW I669296 B 20190821; US 2017159195 A1 20170608; WO 2016030290 A1 20160303

DOCDB simple family (application)

EP 14182083 A 20140825; CN 201580044927 A 20150821; EP 15753055 A 20150821; EP 2015069234 W 20150821; JP 2017511313 A 20150821; KR 20177004453 A 20150821; SG 11201700461V A 20150821; TW 104127802 A 20150825; US 201515327389 A 20150821